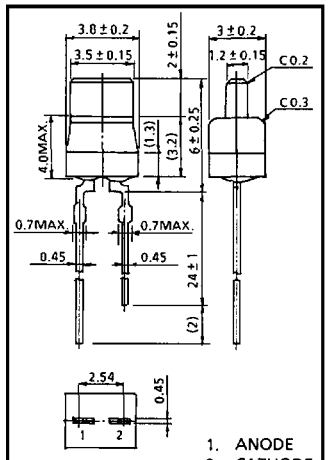
TOSHIBA LED LAMP

TLG210, TLR210, TLY210

PANEL CIRCUIT INDICATOR

Unit in mm



JEDEC	—
EIAJ	—
TOSHIBA	4-4F1A

Weight : 0.13g

- All Plastic Mold Type
- Rectangular Type (Surface Size 1.2×3.5mm)
- Low Drive Current, High Intensity Light Emission.

  Recommended Forward Current : I_F=10~15mA (DC)
- Fast Response Time, Capable of Pulse Operation.

MATERIALS

ITEM / PRODUCT NAME	MATERIALS	LIGHT EMITTING COLOR
TLG210	GaP	Green
TLY210	GaAsP	Yellow
TLR210	GaP	Red

MAXIMUM RATINGS (Ta = 25°C)

ITEM / PRODUCT NAME	FORWARD CURRENT I_F (mA)	REVERSE VOLTAGE V_R (V)	POWER DISSIPATION P_D (mW)	OPERATING TEMPERATURE RANGE T_{opr} (°C)	STORAGE TEMPERATURE RANGE T_{stg} (°C)
TLG210	25	4	70	−20~75	−30~100
TLY210	25	4	70	−20~75	−30~100
TLR210	20	4	56	−20~75	−30~100

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ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

PRODUCT NAME	EMISSION SPECTRUM			LUMINOUS INTENSITY I_V			FORWARD VOLTAGE V_F			REVERSE CURRENT I_R	
	λ_p	$\Delta\lambda$	I_F	MIN.	TYP.	I_F	TYP.	MAX.	I_F	MAX.	V_R
TLG210	565	25	10	0.8	1.5	10	2.15	2.8	20	5	4
TLY210	585	32	10	0.5	1.3	10	2.05	2.8	20	100	4
TLR210	700	100	10	0.4	0.8	10	2.15	2.8	20	5	4
Unit	nm		mA	mcd		mA	V		mA	μA	V

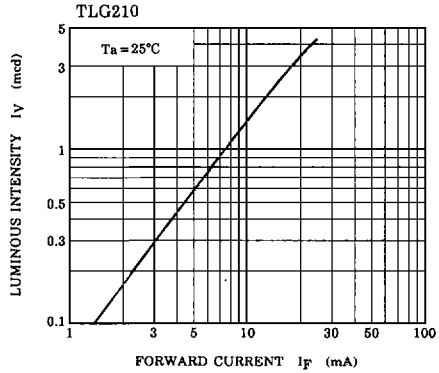
PRECAUTION

Please be careful of the followings.

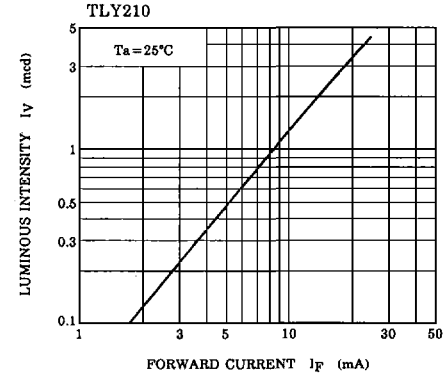
- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
  (Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

$I_V - I_F$

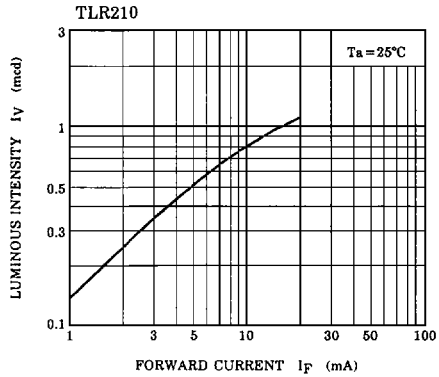
TLG210



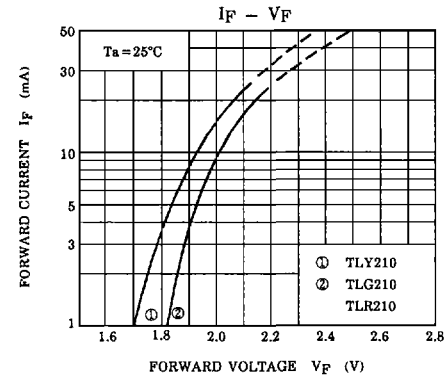
TLY210



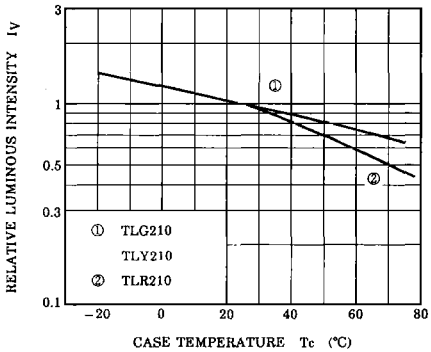
TLR210



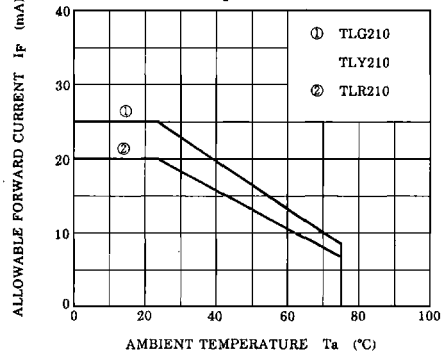
$I_F - V_F$



I_V – Ta



I_F – Ta



RELATIVE LUMINOUS INTENSITY – WAVE LENGTH